FORESEE DDR4 SO-DIMM
2933 Datasheet

Version: 1.0

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Revision History

Revision No.	History	Draft Date	Remark
1.0	Release	Dec 2019	

1. Type

DDR4 SO-DIMM 260PIN

2. Full conception

DDR4 SDRAM Unbuffered DIMM, It supports 1.2V low voltage mode. Design 260PIN golden finger interface protocols, and it supports two dual channel applications.

3. Design refer

JEDEC DDR4 R/C

4. Product Name

Laptop Memory

5. Capacity information

DDR4 8GB

6. Book Sheet

Type	Capacity	Speed	HV P/N
SO-DIMM	8 GB	2933	FD4AS2933C8GSC

7. Specification

Specification	JEDEC DDR4 Reference
Interface	DDR4 260PIN SO-DIMM
Capacity	8 GB
Speed	2933Mbps
CAS Latency	21
Organization	1 Rank x8
Voltage	1.2V
Operating Temp.	0~85℃ (Surface)
Storage Temp.	-40℃ ~ +85℃
Form Factor	69.6 * 30 mm
Application	Laptop （general reference）

8. PCB Specifications

General
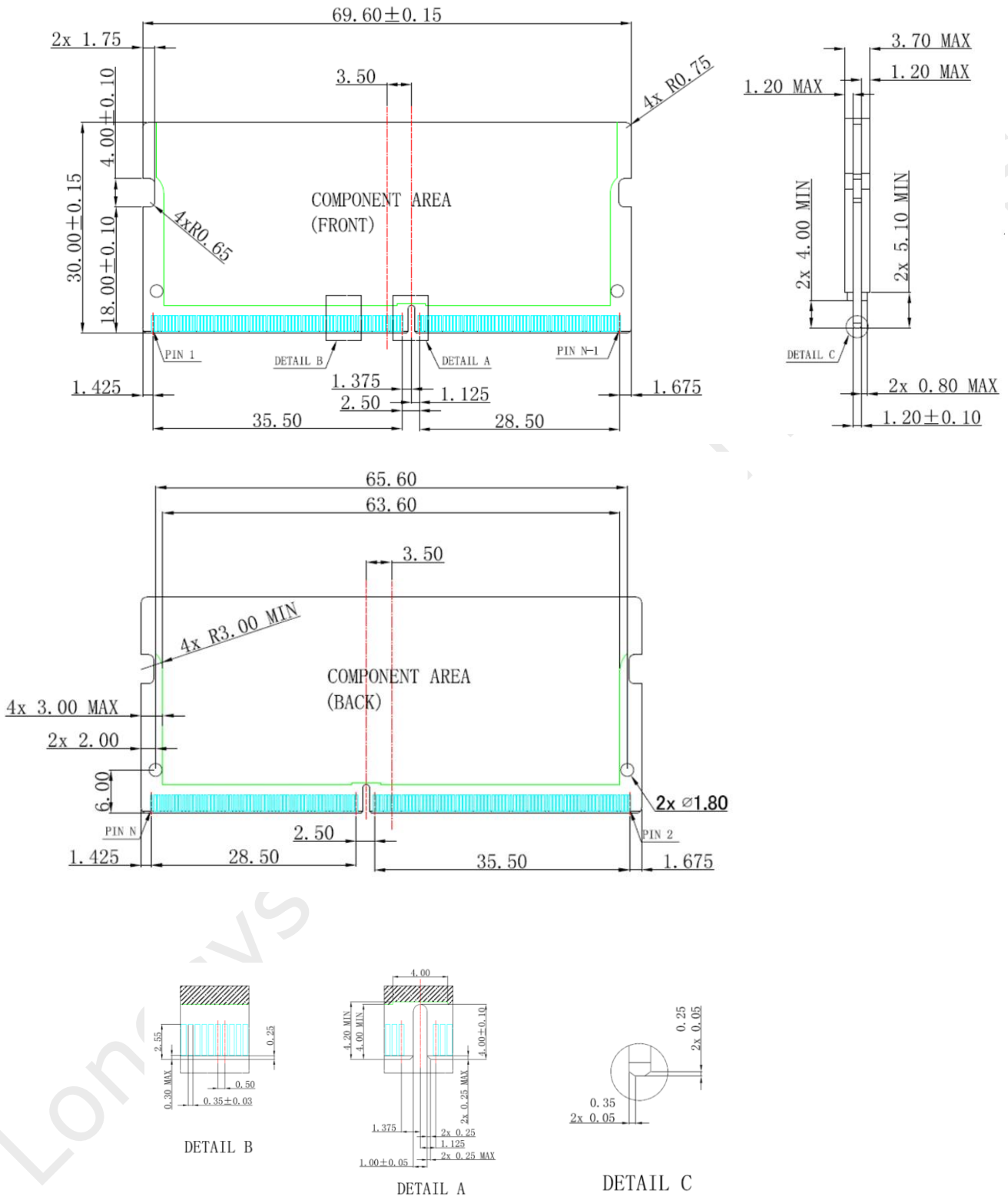
1. Board size：69.6 x 30 mm　　± 0.15 mm

2. Thickness：1.2 ± 0.1 mm

3. Pin count：260 PIN

PCB Material

1. RoHS

2. Glass Epoxy FR4, .UL 94V-0

9. Module Dimensions

Units: millimeters